

## FPC1323

The FPC1323 sensor is using an improved image capture technology that enables even better image capture over a wide range of different finger types and conditions. The FPC1323 sensor support secure transmission of images both protected with integrity and ciphering. Fingerprints' T-shape module is adopted for existing industry standard process delivered on 35 mm reel (dual-row), enabling high volume mass production, high reliable implanting for a low total card cost. The T-shape is created to fit existing mill and drill mass production making an aesthetic design integration of the sensor in the card possible. Compact size and ultra-low power consumption makes it optimal to use in contact or contactless applications.

PARAMETER	DESCRIPTION	VALUE	UNIT
Interface		Half-duplex SPI	Max 4MHz
Supply voltage	VDD voltage, typical	1.8	V
Supply current	Image capture, typical	4.0	mA
Supply current Sleep Mode	With 1s finger detection polling	9	μΑ
Sensor ESD protection	IEC61000-4-2, level X , air discharge	±15	kV
Sensor Wear-and-tear	No of wear cycles at 0.6N	>10 million	times
Operating temperature		-40 to +85	°C
Dimensions, T-shape	$W \times L \times H$	13.2*13.5*0.5	mm

## **TOUCH SENSOR FPC1323 T-SHAPE**

## **FEATURES:**

- (>) Compact standalone biometric module (SiP)
- Ompatible with soldering, ACF and other interconnect technologies
- > Ultra-thin package: 500 μm
- Developed to comply with ISO 7816-1 smartcards
- Excellent 3D image quality
- Superior imaging quality with 256 true grey scale values in every pixel
- Bendable: Robust and fulfill industry standard requirements
- (>) Compact and easy to integrate
- Robust protective coating capable of more than 10 million finger placements
- Full ESD protection to more than +/-15kV
- > Ultra-low power consumption
- > 1.8 V operation
- FPC1323 T-shape available on 35 mm reel dual-row

